	N CONNECTING IN CONNECTING IN DUSTRIES® International and Par	osition Dec PC, Bannockt n-American co	claration ourn, Illinois. A opyright conve	All rights reserved untions.	inder both	This docume level parts, t	ent is a declarat he declaration o	ion of the encompass	substances ses all lowe	within the er level mat	manufactur erials for wh	er listed it hich the m	em. Note: i anufacture	if the item is an as r has engineering	sembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					eous Materia	als and Mfg Information				
Supplier	r Information															
Company name* Company un				nique ID			Unique ID Authority					Response Date*				
On Semico	onductor											2021-02-03				
Contact N	ame	Title - Contact			]	Phone - Contact*					Email - Contact*					
Product-H	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*						
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date	e Versio	n	Manufacturing Site		N	Weight*	UOM	Unit Type	
	D44H11G		BIP T0220 NPN 10A 80V		2021-02-03			CN5		1	962.01	mg	Each			
/anufa	cturing Proccess Informa	tion												I		
	Terminal Plating / Grid Array M	Ferminal Base Alloy J-STD-020 MS		J-STD-020 MSI	Rating	Peak Process Body Temperat		ure Max Time at Peak Tempe		Temperat	ure Numb	ber of Reflow Cyc	les			
Matte Tin (Sn) - annealed			CU Alloy NA				0 C 30				seconds 3					
omments	5															
or more	information regarding material	composition	please refer to	o page 3												

RoHS Material Composition Declaration			Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	А	Lead (Pb)	7439-92-1	7a	78.831	mg
			Supplier	Tin (Sn)	7440-31-5		4.149	mg
Lead Frame	1300.04	mg	Supplier	Copper (Cu)	7440-50-8		1300.04	mg
Mold Compound-Black	543.9	mg		Brominated epoxy resin	proprietary data		10.878	mg
			Supplier	Phenolic Resin	Proprietary Data		27.195	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		16.317	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		435.12	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		54.39	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg